



CST60P02D P-Ch 20V Fast Switching MOSFETs

- ★ Super Low Gate Charge
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

CST60P02D Product Summary



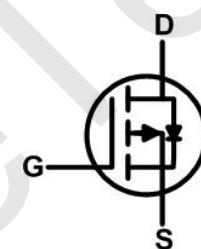
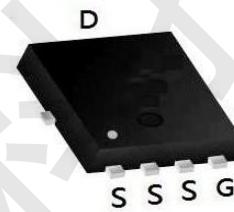
BVDSS	RDSON	ID
-20V	6mΩ	-60A

CST60P02D Description

The CST60P02D is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The CST60P02D meet the RoHS and Green Product requirement with full function reliability approved.

CST60P02D PDFN3333-8L Pin Configuration



CST60P02D Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-20	V
Gate-Source Voltage	V_{GS}	± 10	V
Continuous Drain Current $T_c=25^\circ\text{C}$	I_D	-60	A
$T_c=100^\circ\text{C}$	I_D	-34.8	
Pulsed Drain Current ¹	I_{DM}	-220	A
Single Pulse Avalanche Energy ²	E_{AS}	61.25	mJ
Total Power Dissipation $T_c=25^\circ\text{C}$	P_D	39	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

CST60P02D Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	38	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	3.2	°C/W



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CST60P02D Electrical Characteristics ($T_J = 25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = -250\mu\text{A}$	-20	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 10\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current $T_J=25^\circ\text{C}$	I_{DSS}	$V_{\text{DS}} = -20\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	-1	μA
$T_J=100^\circ\text{C}$			-	-	-100	
Gate-Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_{\text{D}} = -250\mu\text{A}$	-0.4	-	-1.0	V
Drain-Source on-Resistance ⁴	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = -4.5\text{V}, I_{\text{D}} = -15\text{A}$	-	6	8.2	$\text{m}\Omega$
		$V_{\text{GS}} = -2.5\text{V}, I_{\text{D}} = -10\text{A}$	-	7.5	10	
		$V_{\text{GS}} = -1.8\text{V}, I_{\text{D}} = -8\text{A}$	-	10.2	15	
Forward Transconductance ⁴	g_{fs}	$V_{\text{DS}} = -5\text{V}, I_{\text{D}} = -15\text{A}$	-	78	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{\text{DS}} = -10\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	3560	-	pF
Output Capacitance	C_{oss}		-	500	-	
Reverse Transfer Capacitance	C_{rss}		-	430	-	
Gate Resistance	R_g	$f = 1\text{MHz}$	-	11	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{\text{GS}} = -4.5\text{V}, V_{\text{DS}} = -10\text{V}, I_{\text{D}} = -15\text{A}$	-	43	-	nC
Gate-Source Charge	Q_{gs}		-	7.9	-	
Gate-Drain Charge	Q_{gd}		-	11.2	-	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{GS}} = -4.5\text{V}, V_{\text{DD}} = -10\text{V}, R_g = 3\Omega, I_{\text{D}} = -15\text{A}, t_{\text{f}} = 1\text{MHz}$	-	14.5	-	ns
Rise Time	t_r		-	20.2	-	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		-	93	-	
Fall Time	t_f		-	161	-	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -15\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	-	28	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	25.7	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = -1\text{A}, V_{\text{GS}} = 0\text{V}$	-	-	-1.2	V
Continuous Source Current	I_S	$T_C = 25^\circ\text{C}$	-	-	-60	A

Notes:

- Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.
- The EAS data shows Max. rating . The test condition is $V_{\text{DD}} = -25\text{V}, V_{\text{GS}} = -10\text{V}, L = 0.1\text{mH}, I_{\text{AS}} = 35\text{A}$.
- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
- This value is guaranteed by design hence it is not included in the production test.



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CST60P02D Typical Characteristics

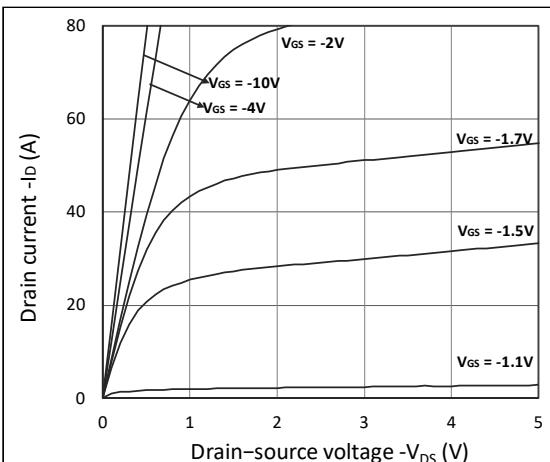


Figure 1. Output Characteristics

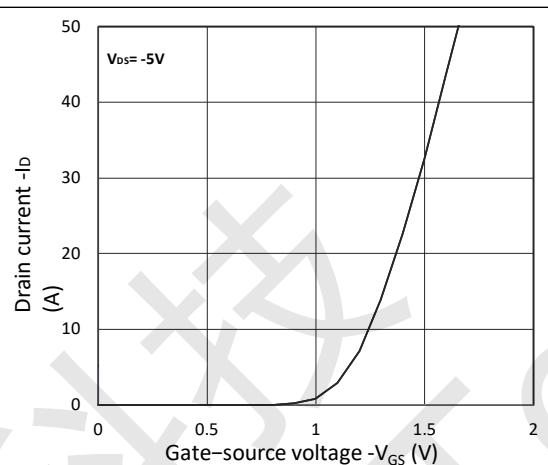


Figure 2. Transfer Characteristics

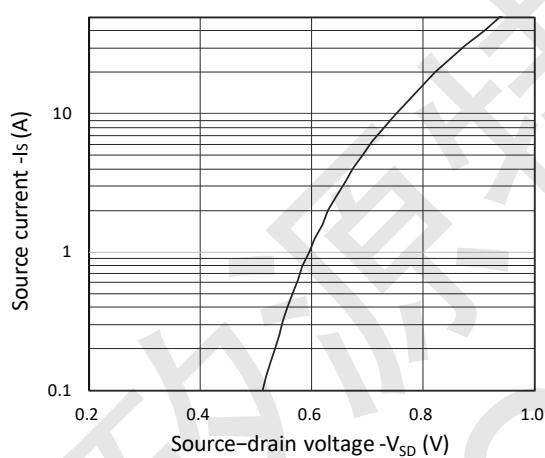


Figure 3. Forward Characteristics of Reverse

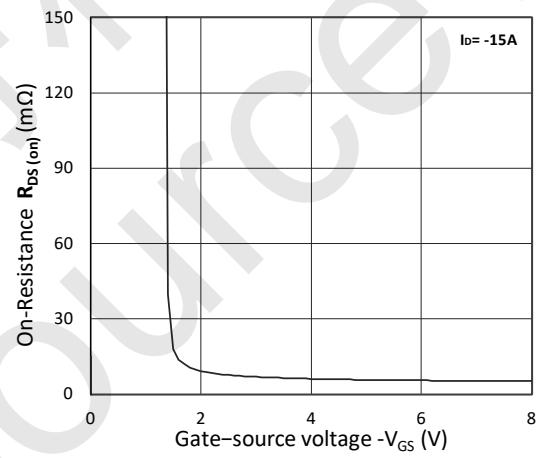


Figure 4. $R_{DS(on)}$ vs. V_{GS}

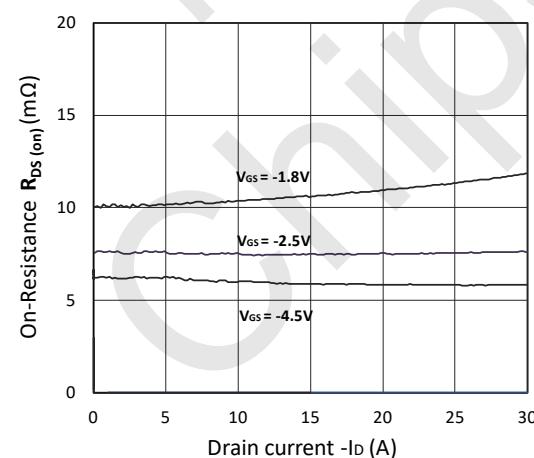


Figure 5. $R_{DS(on)}$ vs. I_D

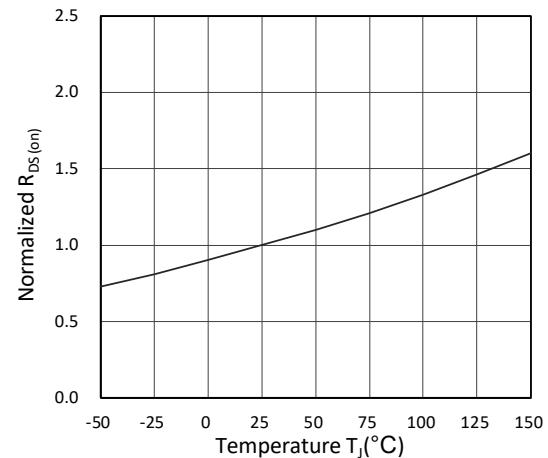


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature



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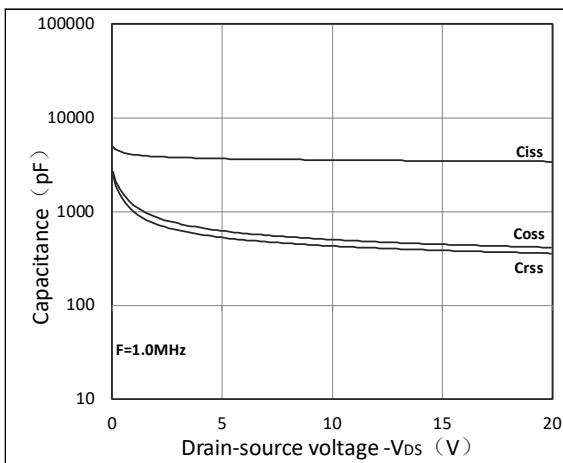


Figure 7. Capacitance Characteristics

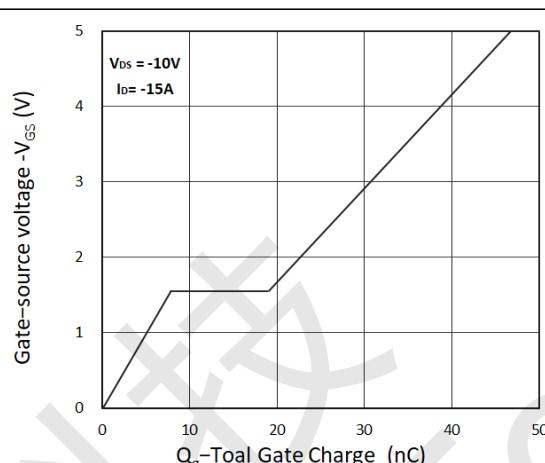


Figure 8. Gate Charge Characteristics

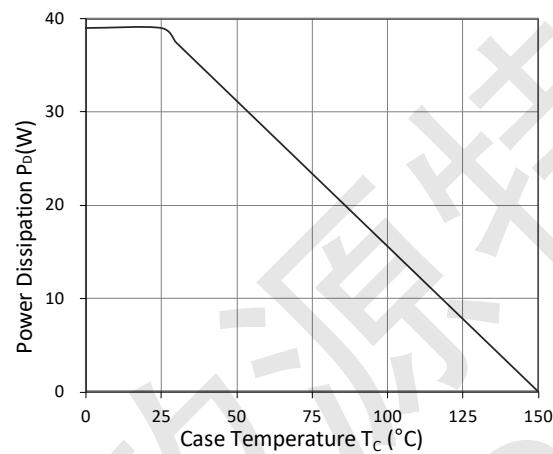


Figure 9. Power Dissipation

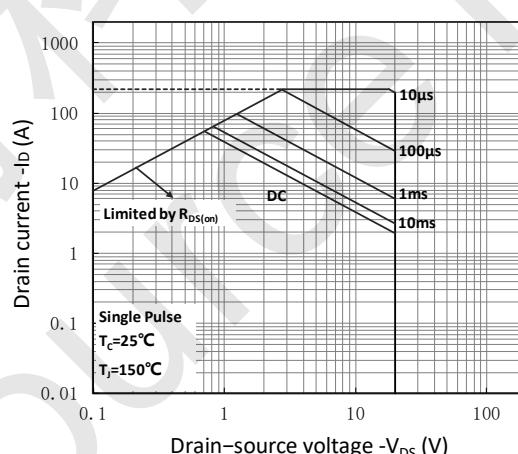


Figure 10. Safe Operating Area

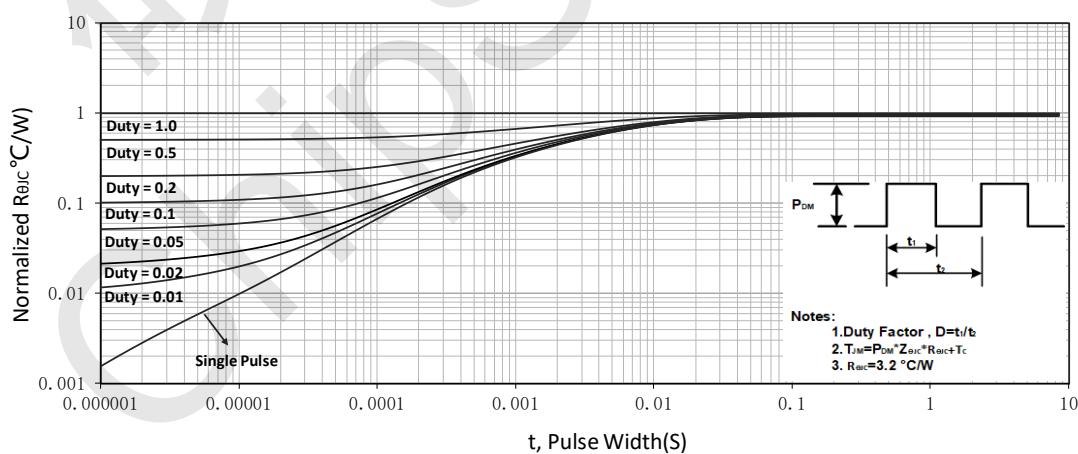


Figure 11. Normalized Maximum Transient Thermal Impedance



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CST60P02D Test Circuit

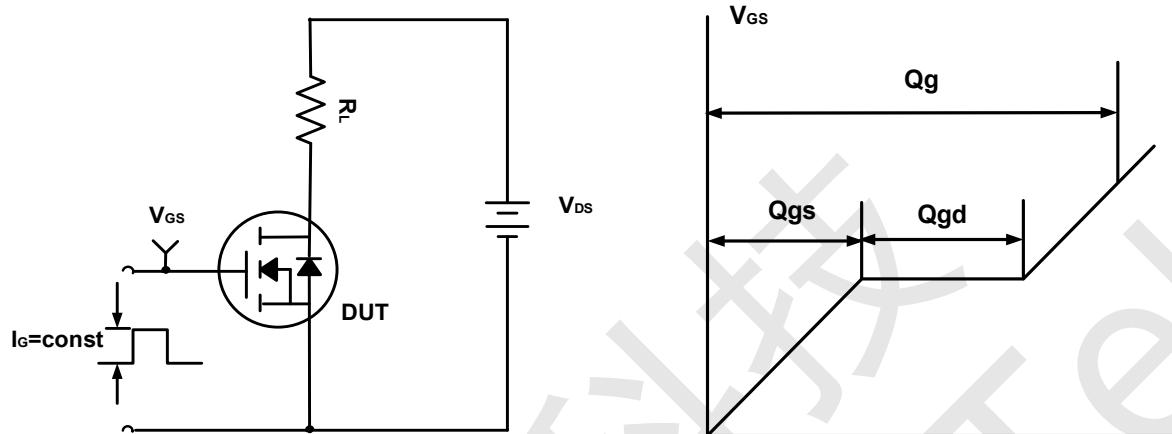


Figure A. Gate Charge Test Circuit & Waveforms

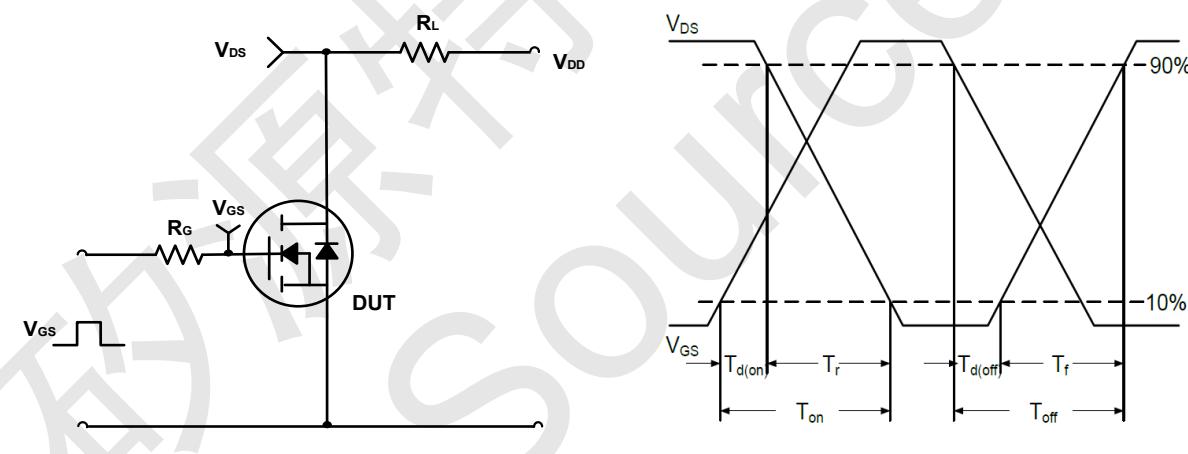


Figure B. Switching Test Circuit & Waveforms

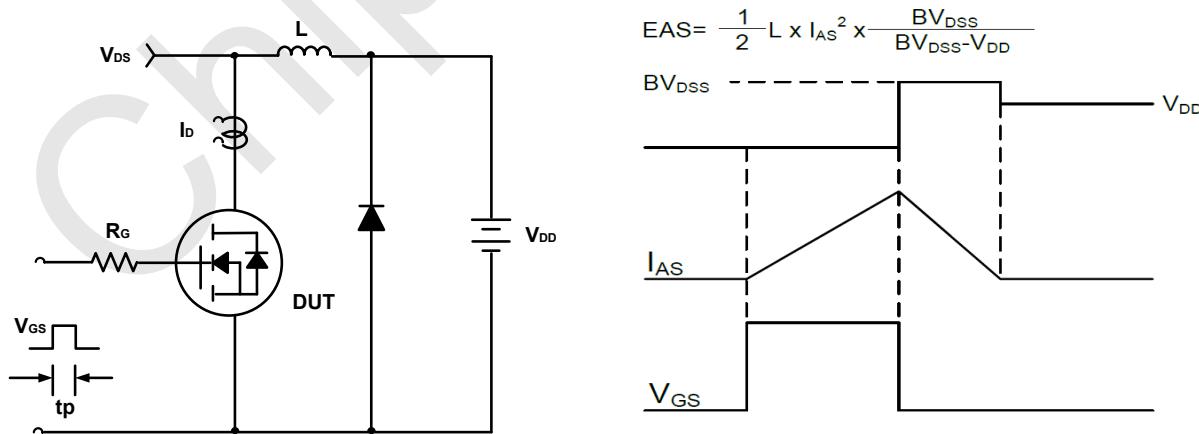


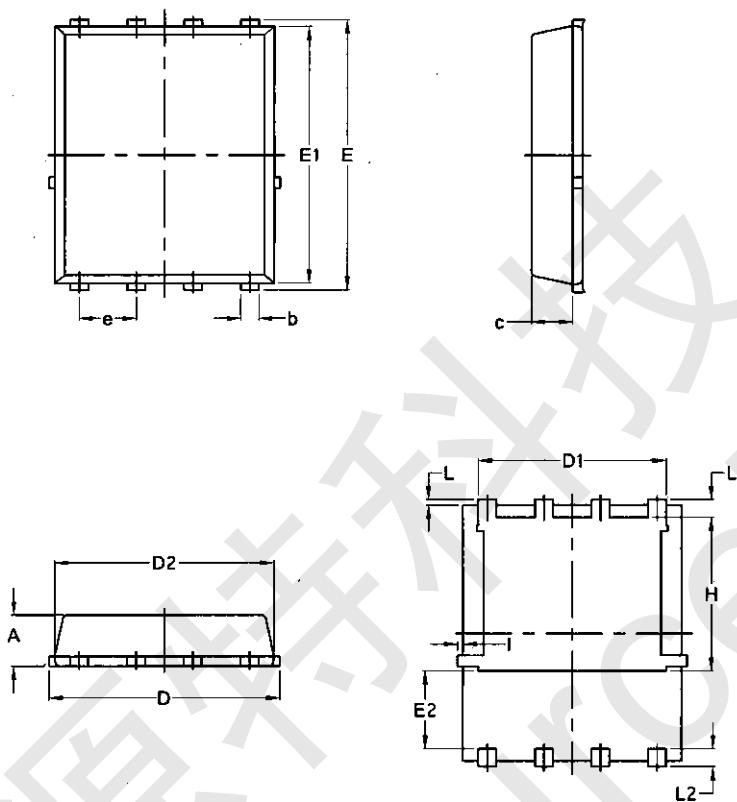
Figure C. Unclamped Inductive Switching Circuit & Waveforms



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CST60P02D Package Mechanical Data-PDFN3333-8L-Single



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	0.70	0.80	0.90
A1	0.00	0.03	0.05
b	0.24	0.30	0.35
c	0.10	0.15	0.20
D	3.25	3.32	3.40
D1	3.05	3.15	3.25
D2	2.40	2.50	2.60
E	3.00	3.10	3.20
E1	1.35	1.45	1.55
e	0.65 BSC.		
H	3.20	3.30	3.40
L	0.30	0.40	0.50
L1	0.10	0.15	0.20
L2	1.13 REF.		